

## **APPLICATION DATA SHEET**

### **Application Information**

Application Type::	Regular
Subject Matter::	Utility
Title::	Lead Frame, Resin Sealing Mold And Method For Manufacturing A Semiconductor Device Using The Same
Attorney Docket Number::	2905-107
Request for Early Publication?::	No
Request for Non-Publication?::	No
Total Drawing Sheets::	Fifteen (15)
Small Entity::	No
Petition included?::	No
Secrecy Order in Parent Appl?::	No

### **Applicant Information**

Applicant Authority type::	Inventor
Primary Citizenship Country::	Japan
Status::	Full Capacity
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Middle Name::	-----
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Country of Residence::	Japan
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Applicant Authority type:: Inventor  
Primary Citizenship Country:: Japan  
Status:: Full Capacity  
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Middle Name:: -----  
Family Name:: Onda  
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#### **Assignment Information**

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**Domestic Priority Information**

Application::	Continuity Type:	Parent Application:	Parent Filing Date:
This Application	Divisional	10/291,815	11/12/02

**Foreign Priority Information**

Country::	Application Number::	Filing Date::	Priority Claimed::
Japan	2002-020296	01/29/02	Yes
Japan	2001-346408	11/12/01	Yes

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